



Material Content Data Sheet



Sales Product Name				IPD50P04P4L-11		Issued		26. September 2017	
MA#				MA000760004					
Package				PG-TO252-3-313		Weight*		317.62 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.525	0.48	0.48	4801	4801	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		464		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139		
	non noble metal	copper	7440-50-8	147.096	46.31	46.37	463127	463730	
wire	non noble metal	aluminium	7429-90-5	2.160	0.68	0.68	6801	6801	
encapsulation	organic material	carbon black	1333-86-4	1.407	0.44		4429		
	plastics	epoxy resin	-	24.620	7.75		77516		
	inorganic material	silicondioxide	60676-86-0	114.660	36.10	44.29	361005	442950	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11775	11775	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4472	4483	
solder	noble metal	silver	7440-22-4	0.040	0.01		125		
	non noble metal	tin	7440-31-5	0.032	0.01		100		
	non noble metal	lead	7439-92-1	1.517	0.48	0.50	4777	5002	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.04	6.05	60380	60458	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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